

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ520N15NS3 G	**Issued**	25. January 2018
MA#	MA001868650		
Package	PG-TSDSON-8-2	**Weight***	38.76 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	4.73	4.73	47343	47343
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		54	
	non noble metal	zinc	7440-66-6	0.008	0.02		216	
	non noble metal	iron	7439-89-6	0.168	0.43		4326	
	non noble metal	copper	7440-50-8	6.808	17.57	18.03	175650	180246
wire	non noble metal	copper	7440-50-8	0.037	0.09	0.09	945	945
encapsulation	organic material	carbon black	1333-86-4	0.034	0.09		868	
	plastics	epoxy resin	-	1.733	4.47		44725	
	inorganic material	silicondioxide	60676-86-0	15.062	38.88	43.44	388633	434226
leadfinish	non noble metal	tin	7440-31-5	0.387	1.00	1.00	9989	9989
plating	noble metal	silver	7440-22-4	0.963	2.48	2.48	24836	24836
solder	non noble metal	tin	7440-31-5	0.037	0.10		950	
	noble metal	silver	7440-22-4	0.046	0.12		1187	
	non noble metal	lead	7439-92-1	1.758	4.53	4.75	45349	47486
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		111	
	non noble metal	iron	7439-89-6	0.086	0.22		2225	
	non noble metal	copper	7440-50-8	3.501	9.03	9.26	90336	92700
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		195	
	non noble metal	iron	7439-89-6	0.151	0.39		3893	
	non noble metal	copper	7440-50-8	6.127	15.81	16.22	158092	162229
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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